

# 1.5A, 200V - 600V High Efficient Surface Mount Rectifier

#### **FEATURES**

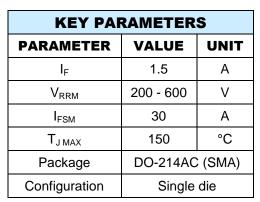
- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- · Fast switching for high efficiency
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

#### **MECHANICAL DATA**

- Case: DO-214AC (SMA)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.064g (approximately)











DO-214AC (SMA)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	SYMBOL	BYG20DH	BYG20GH	BYG20JH	UNIT
Marking code on the device		BYG20D	BYG20G	BYG20J	
Repetitive peak reverse voltage	$V_{RRM}$	200	400	600	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	V
Forward current	I <sub>F</sub>	1.5		Α	
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	30		Α	
Pulse energy in avalanche mode, non-repetitive (Inductive load switch off), L = 120mH	E <sub>RSM</sub>	20		mJ	
Junction temperature	$T_J$	- 55 to +150		°C	
Storage temperature	T <sub>STG</sub>	- 55 to +150		°C	

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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	25	°C/W
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	100	°C/W

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	$I_F = 1.0A, T_J = 25^{\circ}C$	V <sub>F</sub>	-	1.3	V
	$I_F = 1.5A, T_J = 25^{\circ}C$		-	1.4	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C	l <sub>R</sub>	-	1	μA
	T <sub>J</sub> = 100°C		-	10	μΑ
Reverse recovery time	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$	t <sub>rr</sub>	-	75	ns

#### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
BYG20xH	DO-214AC (SMA)	7,500 / Tape & Reel	

#### Notes:

1. "x" defines voltage from 200V(BYG20DH) to 600V(BYG20JH)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

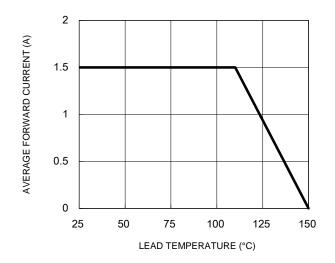


Fig.3 Typical Reverse Characteristics

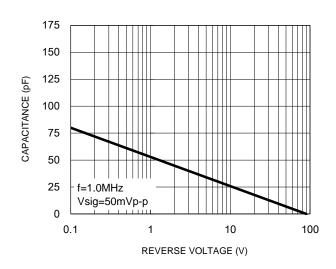
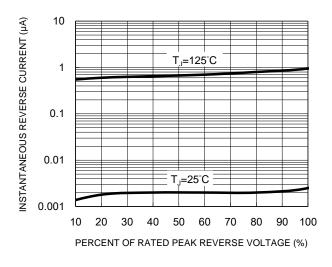


Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics



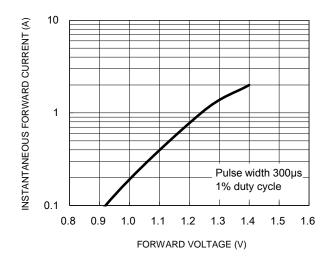
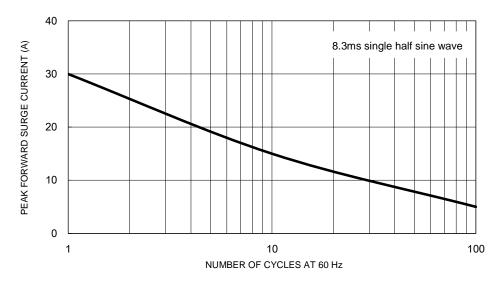


Fig.5 Maximum Non-Repetitive Forward Surge Current

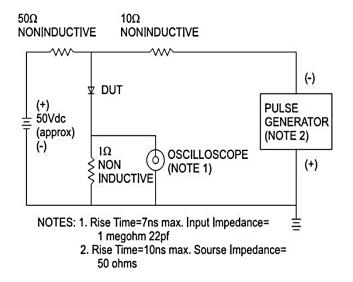


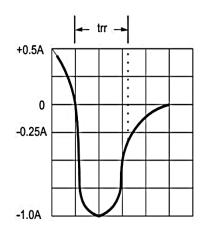


### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

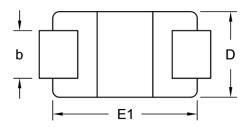


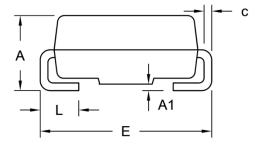




## **PACKAGE OUTLINE DIMENSIONS**

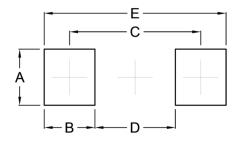
# DO-214AC (SMA)





DIM.	Unit (mm)		Unit (	(inch)
Dilvi.	Min.	Max.	Min.	Max.
Α	1.99	2.50	0.078	0.098
A1	0.10	0.20	0.004	0.008
b	1.27	1.58	0.050	0.062
С	0.15	0.31	0.006	0.012
D	2.29	2.83	0.090	0.111
E	4.95	5.33	0.195	0.210
E1	4.06	4.60	0.160	0.181
L	0.90	1.41	0.035	0.056

### **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.68	0.066
В	1.52	0.060
С	3.93	0.155
D	2.41	0.095
E	5.45	0.215

# **MARKING DIAGRAM**



P/N = Marking Code G = Green Compound

YW = Date Code F = Factory Code



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